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TABLE OF CONTENTS

ALD – A FINNISH GEM OF TECHNOLOGY

Power of ALD and Secrets Behind It	1
<i>Mikko Ritala</i>	
ALD for Sustainable Future – Paving the Way to Cleaner World from Sub-nanometer Level	2
<i>Minna Toivola, T. Pilvi</i>	
ALD Coating at Lower Temperature for Polymers and Carbon Nanotube Based Transistors.....	6
<i>Kestutis Grigoras</i>	
From R&D Towards Industrial Atomic Layer Deposition in MEMS Applications.....	12
<i>Markus Bosund, M. Putkonen</i>	
Picosun SUNALE™ ALD Systems for High Quality Nanocoatings – Bridging the Gap Between R&D and Industrial Production.....	18
<i>Minna Toivola, T. Lehto, W-M. Li, T. Pilvi, P. J. Soininen</i>	

FLIP CHIP

New Flip Chip Technologies	22
<i>Reinhard Windemuth</i>	
Electroless Nickel and Immersion Gold deposition on Single Chips for Flip Chip Assembly of Pixel Detectors.....	36
<i>Akiko Gädda, Jaakko Salonen, Tommi Suni, Sami Vähänen, Philippe Monnoyer, Hannele Heikkinen, Harri Pohjonen</i>	
New Approach Into High Accuracy and High Volumes Flip Chip Attachment.....	45
<i>Klaus Turhanen</i>	

ADVANCED TECHNOLOGIES

Embedding Technology for Manufacturing of High Density SiP	52
<i>Lars Boettcher, S. Karaszewics, D. Manassis, A. Ostmann</i>	
Plasma Dicing Technology – Next Solution for Ultra-thin Wafer & Tiny Chips	59
<i>Mitsuru Hiroshima, Atsushi Harikai</i>	
LED SSL Packaging Study with LED Device Teardown	73
<i>Tetsuya Onishi</i>	

HIGH FREQUENCY, PASSIVES, MEMS

GaN/SiC Components and RF Power Amplifier Modules – Results and Challenges	88
<i>Martin Oppermann</i>	
Need for Active Design of Passives	92
<i>Olivier Gaborieau, Paul Collander</i>	
LTCC Packaging from RF to Millimeter Waves	96
<i>Markku Lahti, K. Kautio, V. Kondratyev, M. Kaunisto, T. Vähä-Heikkilä</i>	
Development of Methods for Reliability Assessment of 3-Axial MEMS Gyroscopes.....	102
<i>Jussi Hokka, Hannes Hyvönen, Jue Li, Toni T. Mattila, Mervi Paulasto-Kröckel</i>	

INTERCONNECTION TECHNOLOGIES

A Study on the Microstructure of Sn-Ag-Cu Lead-Free Solder Joints in Pulse-Heated Reflow Soldering.....	108
<i>Milad Mostofizadeh, K Kokko, L. Frisk</i>	
Depoling of PZT-Materials during Batch Soldering Processes.....	117
<i>Silke Bramlage, Klaus-Jürgen Wolter</i>	
Cu Wire Bonding Trend & Overview at Asia	N/A
<i>Tetsuya Onishi H. Tabata, M. Chino</i>	
Author Index	